

ABSTRACT

A semiconductor device characterized in that
connection pads for wire bonding are arranged at
5 peripheral regions of an electrode terminal formation
surface of a semiconductor chip, test pads for testing
the semiconductor chip are arranged in an inside region
surrounded by said peripheral regions of said electrode
terminal formation surface, and a plurality of rewiring
10 patterns extend from the peripheral regions to said
inside region of said electrode terminal formation
surface and the individual rewiring patterns connect the
individual electrode terminals and the corresponding
connection pads and test pads.